



# FRED Ultrafast Soft Recovery Diode, 2 x 30 A

### **FEATURES**

- Ultrafast recovery
- Ultrasoft recovery
- Very low I<sub>RRM</sub>
- Very low Q<sub>rr</sub>
- · Specified at operating conditions
- · Designed and qualified for industrial level

#### **BENEFITS**

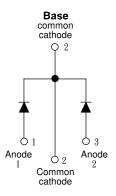
- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

### **DESCRIPTION**

HFA60PA40C is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 400V and 30 A per leg continuous current, the HFA60PA40C is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the FRED product line features extremely low values of peak recovery current (IRRM) and does not exhibit any tendency to "snap-off" during the tb portion of recovery. The FRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These FRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The FRED HFA60PA40C is ideally suited for applications in power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.



TO-247 AB



PRODUCT SUMMARY					
$V_R$	400 V				
V <sub>F</sub> at 30A at 25 °C	1.3 V				
I <sub>F(AV)</sub>	2 x 30 A				
t <sub>rr</sub> (typical)	22 ns				
T <sub>J</sub> (maximum)	150 °C				
Q <sub>rr</sub> (typical)	49 nC				
I <sub>RRM</sub> (typical)	3.0 A				

ABSOLUTE MAXIMUM RATINGS								
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Cathode to anode voltage		$V_R$		400	V			
Maximum continuous forward current	per leg	- I <sub>F</sub>	T <sub>C</sub> = 100 °C	30				
waximum continuous forward current	per device			60	Α			
Single pulse forward current		I <sub>FSM</sub>		320				
Operating junction and storage temperature	T <sub>J</sub> , T <sub>Stg</sub>		- 55 to + 150	°C				



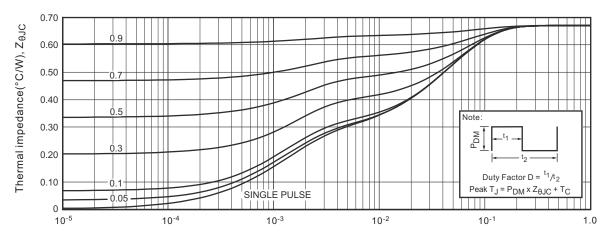
ELECTRICAL SPECIFIC	ATIONS	G (T <sub>J</sub> = 25 °C unless otherwise specified)				
PARAMETER	SYMBOL	TEST CONDITIONS		TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	$V_{BR}$	I <sub>R</sub> = 100 μA	400	-	-	
Maximum forward voltage V <sub>FM</sub>		I <sub>F</sub> = 30 A	-	1.3	1.5	V
	$V_{FM}$	I <sub>F</sub> = 60 A	-	1.6	-	
		I <sub>F</sub> = 30 A, T <sub>J</sub> = 125 °C	-	1.2	-	
Maximum reverse	Maximum reverse	V <sub>R</sub> = V <sub>R</sub> rated	-	-	100	
leakage current	I <sub>RM</sub>	$T_J = 125$ °C, $V_R = V_R$ rated	-	-	500	μΑ
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 200V	-	60	-	pF
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body	-	12	-	nH

DYNAMIC RECOVERY CHARACTERISTICS PERLEG (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST C	MIN.	TYP.	MAX.	UNITS	
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 0.5A, I <sub>R</sub> = 1.0A, I <sub>RF</sub>	I <sub>R</sub> = 1.0A, I <sub>RR</sub> = 250mA (RG#1 CKT)		28	35	- ns
		$I_F = 1.0 \text{ A}, dI_F/dt = -100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}, T_J = 25^{\circ}\text{C}$		-	22	-	
	t <sub>rr1</sub>	T <sub>J</sub> = 25 °C	I <sub>F</sub> = 30A dI <sub>F</sub> /dt = -200 A/μs V <sub>R</sub> = 266 V	-	32	50	- A
	t <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	95	-	
Peak recovery current	I <sub>RRM1</sub>	T <sub>J</sub> = 25 °C		-	3	-	
	I <sub>RRM2</sub>	T <sub>J</sub> = 125 °C		-	7	-	
Reverse recovery charge	Q <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	49	-	nC
	Q <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	360	-	

THERMAL - MECHANICAL SPECIFICATIONS PER LEG							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Lead temperature	T <sub>lead</sub>	0.063" from case (1.6 mm) for 10 s	-	-	300	°C	
Junction to case, single leg conduction	В		-	-	0.67		
Junction to case, both legs conducting	- R <sub>thJC</sub>		-	-	0.34	KAA	
Thermal resistance, junction to ambient	R <sub>thJA</sub>	Typical socket mount	-	-	40	K/W	
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.25	-		
Weight			-	6.0	-	g	
			-	0.21	-	OZ.	
Mounting torque			6.0 (5.0)	-	12 (10)	kgf . cm (lbf . in)	
Marking device		Case style TO-247AB (JEDEC)	HFA60PA40C				



Fig.1 Maximum effective transient thermal impedance, junction-to-case vs. pulse duration



Rectangular pulse duration (seconds)

Fig.2 Forward current vs. forward voltage

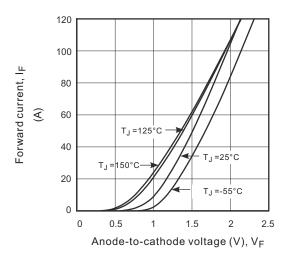


Fig.3 Reverse recovery time vs. current rate of change

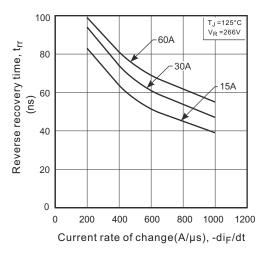


Fig.4 Reverse recovery charge vs. current rate of change

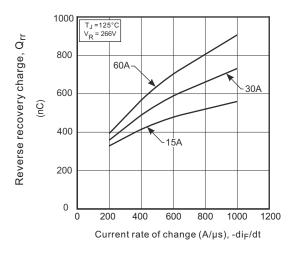


Fig 5. Reverse recovery current vs. current rate of change

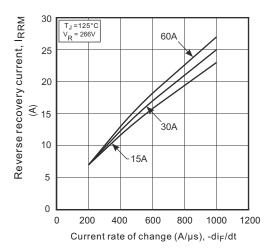




Fig6. Dynamic parameters vs. junction temperature

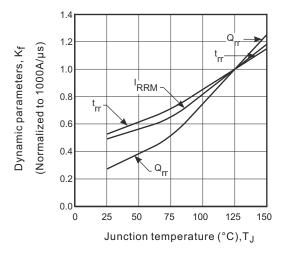


Fig.7 Maximum average forward current vs. case temperature

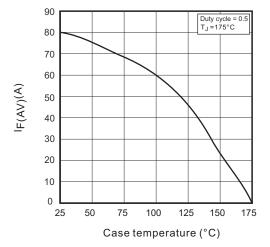
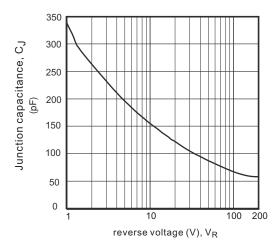


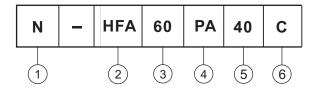
Fig.8 Junction capacitance vs. reverse voltage



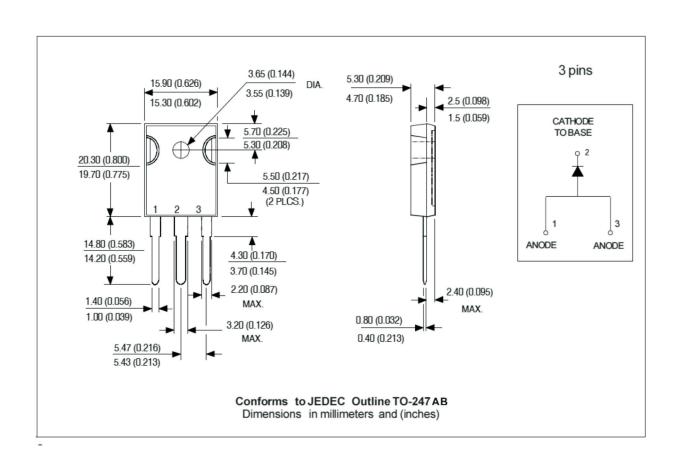


### **ORDERING INFORMATION TABLE**

Device code



- 1 Nell Semiconductors product
- 2 FRED family
- 3 Current rating (60 = 30 A, 30A x 2)
- Package outline (PA = TO-247, 3 pins)
- 5 Voltage rating (40 = 400 V)
- 6 Configuration (C = Center tap common cathode)



www.nellsemi.com